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page)**CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)**Applicant(s): **Masonori MINAMIO**

Docket No.

JEL 30763PCT

Serial No.

09/380,312

Filing Date

August 31, 1999

Examiner

L. C. Cruz

Group Art Unit

2815

Invention:

RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAMEI hereby certify that this signature page of Amendment filed October 17, 2002

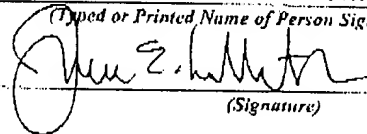
(Identify type of correspondence)

is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. 703-746-8812)on November 5 2002

(Date)

James E. Ledbetter

(Typed or Printed Name of Person Signing Certificate)



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Rejection of Claims 4 and 5

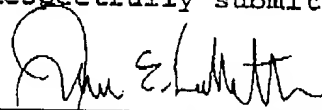
Claims 4 and 5 now recite that the sealing resin contacts a bottom face of the semiconductor chip. This is supported by Figs. 1 and 2, in that in Fig. 2, it is clear that resin 15 contacts the bottom face of chip 12 since chip 12 extends beyond the extent of die pad portion 11.

Neither Morihiro or Kanji discloses or suggests such subject matter. Thus, it is submitted that, due to at least this recited feature, claims 4 and 5 patentably distinguish over Morihiro and Kanji whether considered alone or in combination.

For at least the above reasons, it is respectfully submitted that all grounds of rejection stated in the Office Action have been overcome. A Notice of Allowance is respectfully solicited.

If any issues remain which may be best resolved through a telephone communication, the Examiner is requested to kindly telephone the undersigned at the local, Washington D.C. telephone number listed below.

Respectfully submitted,



James E. Ledbetter
Registration No. 28,732

Date: October 17, 2002

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